



Full Material Declaration for attached parts list

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Declarations authorised by
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Declaration effective from: 30 December 2013 [Approved: 21 February 2025 10:26 GMT]

Individual materials in the part			Individual substances in each material		
Use/Location	Material Group	Max mass %	Substance	CAS Number	Max mass %
Chip (die)	Other inorganic materials	0.12%	Elemental nickel REACH Article 67 Exemption	7440-02-0	0.464%
			GOLD, ELEMENTAL	7440-57-5	0.611%
			ALUMINUM, ELEMENTAL	7429-90-5	0.66%
			Tin elemental	7440-31-5	3.672%
			Silicon	7440-21-3	94.593%
			Carbon black	1333-86-4	1%
			ZINC BORATE	1332-07-6	2.5%
Encapsulation	EP (Epoxy resin)	63.68%	Phenol, polymer with formaldehyde	9003-35-4	5%
			Formaldehyde, polymer with (chloromethyl)oxirane and 2-methylphenol	29690-82-2	7.5%
			Quartz (SiO2) Exempt from other regulatory requirements	14808-60-7	84%
Inner preparation	Copper (e.g. copper amounts in cable harnesses)	0.24%	COPPER, ELEMENTAL	7440-50-8	100%
Leadfinish	Tin plating	1.77%	Tin	7440-31-5	100%
			Silver	7440-22-4	0.5%
Leadframe	Nickel and Nickel alloys	34.19%	Elemental nickel REACH Article 67 Exemption	7440-02-0	40.34%
			Elemental iron	7439-89-6	59.16%

Attached parts list

Part number	Part name
SOD-523 (EB) Pb&H-Free	Diode SMD